

## Description

The DGD0211C single high speed / low side MOSFET and IGBT driver is capable of driving 1.9A of peak current. The DGD0211C logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with MCUs. The DGD0211C provides non-inverting and inverting inputs.

Because of fast propagation times of 35ns typical and rise/fall times of 15ns typical, the DGD0211C is well suited for high speed applications like switch mode power supplies and PFC circuits.

The DGD0211C is offered in TSOT25 package and the operating temperature extends from -40°C to +125°C.

## Features

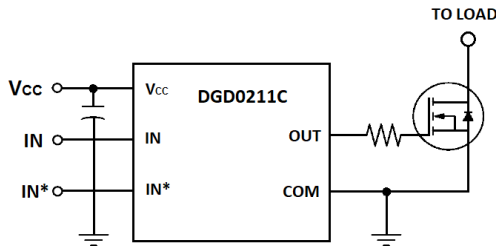
- Efficient Low Cost Solution for Driving MOSFETs and IGBTs
  - Wide Supply Voltage Operating Range: 4.5V to 18V
  - 1.9A Source / 1.8A Sink Output Current Capability
  - Non-Inverting and Inverting Input Configuration
  - Fast Propagation Delay (35ns Typ)
  - Fast Rise and Fall Times (15ns Typ)
  - Logic Input (IN, IN\*) 3.3V Capability
  - Extended Temperature Range: -40°C to +125°C
  - **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
  - **Halogen and Antimony Free. "Green" Device (Note 3)**
  - **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative.**
- <https://www.diodes.com/quality/product-definitions/>

## Applications

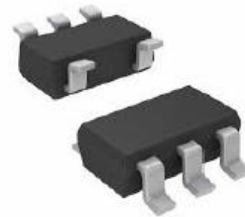
- DC-DC Converters
- Line Drivers
- Motor Controls
- Switch Mode Power Supplies

## Mechanical Data

- Case: TSOT25 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 (e3)
- Weight: 0.012 grams (Approximate)



Typical Configuration



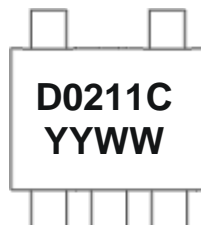
TSOT25

## Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD0211CWT-7	D0211C	7	8	3,000

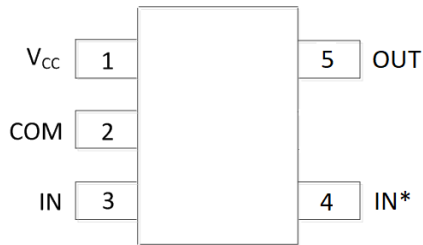
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



D0211C = Product Type Marking Code  
 YY = Year (ex: 20 = 2020)  
 WW = Week (01 to 53)

**Pin Diagrams**

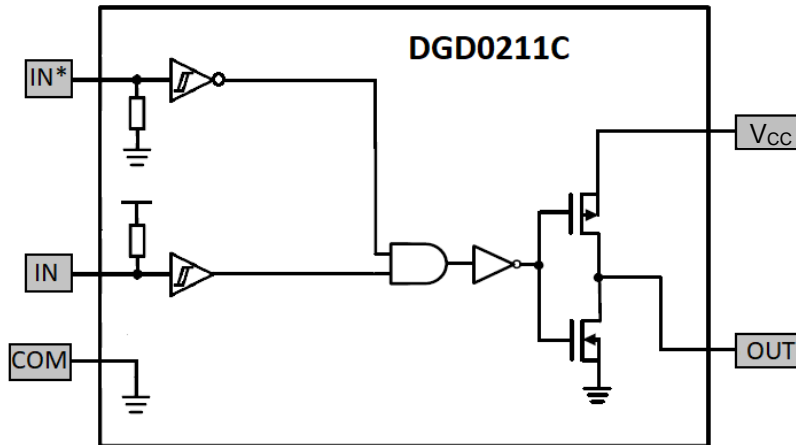


Top View TSOT25

**Pin Descriptions**

Pin Number	Pin Name	Function
1	V <sub>CC</sub>	Supply Input
2	COM	Supply Return
3	IN	Non-Inverting Logic Input, see Input/Output Response Table (Connect to V <sub>CC</sub> to Enable Output)
4	IN*	Inverting Logic Input, see Input/Output Response Table (Connect to COM to Enable Output)
5	OUT	Gate Drive Output

**Functional Block Diagrams**



**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Low-Side Fixed Supply Voltage	V <sub>CC</sub>	-0.3 to +22	V
Output Voltage (OUT)	V <sub>OUT</sub>	-0.3 to V <sub>CC</sub> +0.3	V
Logic Input Voltage (IN, IN*)	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> +0.3	V

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P <sub>D</sub>	0.54	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	188	°C/W
Operating Temperature	T <sub>J</sub>	+150	°C
Lead Temperature (Soldering, 10s)	T <sub>L</sub>	+300	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

**Recommended Operating Conditions**

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V <sub>B</sub>	4.5	18	V
Output Voltage (OUT)	V <sub>S</sub>	0	V <sub>CC</sub>	V
Logic Input Voltage (IN, IN*)	V <sub>IN</sub>	0	5	V
Ambient Temperature	T <sub>A</sub>	-40	+125	°C

**DC Electrical Characteristics** ( $V_{BIAS} (V_{CC}, V_{BS}) = 12V, @T_A = +25^\circ C$ , unless otherwise specified.) (Note 6)

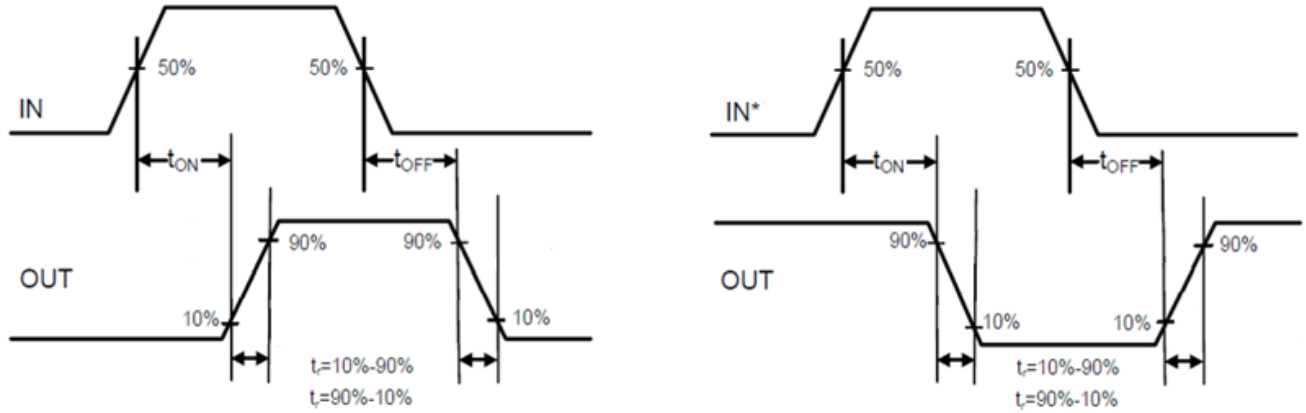
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" Input Voltage	$V_{IH}$	2.4	1.6	—	V	—
Logic "0" Input Voltage	$V_{IL}$	—	1.3	0.8	V	—
Logic "1" Input Bias Current	$I_{IN+}$	—	—	5	$\mu A$	$V_{IN} = 3V, V_{IN^*} = 0V$
Logic "0" Input Bias Current	$I_{IN-}$	—	—	2	$\mu A$	$V_{IN} = 0V, V_{IN^*} = 3V$
High Level Output Voltage, $V_{BIAS} - V_O$	$V_{OH}$	—	25	—	mV	—
Low Level Output Voltage	$V_{OL}$	—	25	—	mV	—
Quiescent $V_{CC}$ Supply Current	$I_{CCQ}$	—	50	100	$\mu A$	$V_{IN} = 0V$ or $3V$
Output High Short Circuit Pulsed Current	$I_{O+}$	—	1.9	—	A	—
Output Low Short Circuit Pulsed Current	$I_{O-}$	—	1.8	—	A	—
Output Reverse Current Withstand	$I_{RVS}$	—	250	—	mA	—

Note: 6. The  $V_{IN}$  and  $I_{IN}$  parameters are applicable to the logic input pin: IN and IN\*. The  $V_O$  and  $I_O$  parameters are applicable to the output pin: OUT.

**AC Electrical Characteristics** ( $V_{CC} = 12V, @T_A = +25^\circ C$ , unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-On Rise Time	$t_r$	—	15	25	ns	$C_L = 1000pF$
Turn-Off Fall Time	$t_f$	—	15	25	ns	$C_L = 1000pF$
Turn-On Propagation Delay	$t_{ON}$	—	35	50	ns	—
Turn-Off Propagation Delay	$t_{OFF}$	—	35	55	ns	—

**Timing Waveforms**

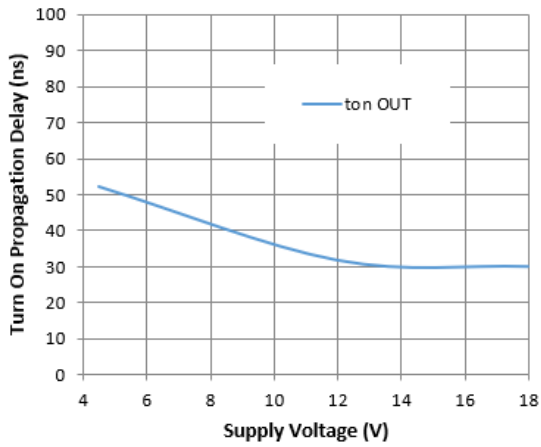


**Figure 1. Switching Time Waveform Definitions**

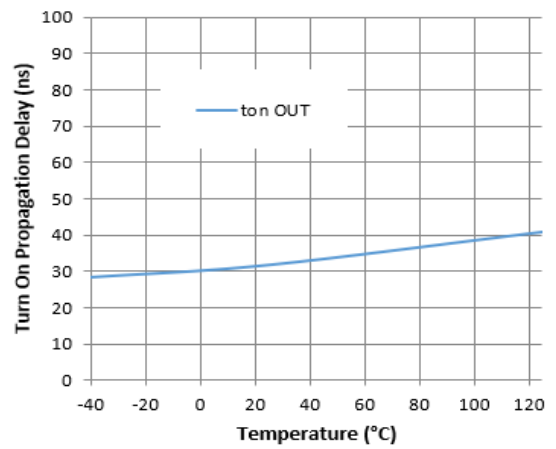
**Input/Output Response Table**

IN	IN*	OUT
0	0	0
0	1	0
1	0	1
1	1	0

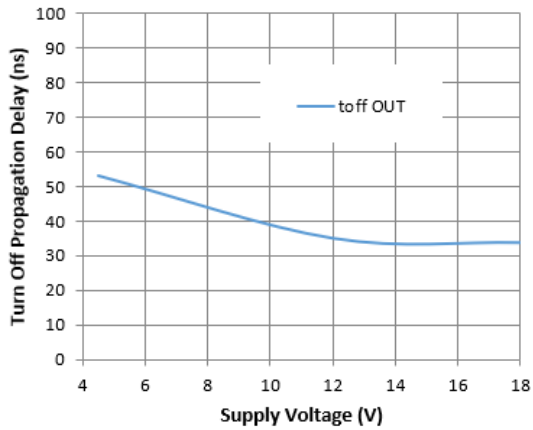
**Typical Performance Characteristics** ( $V_{CC} = 12V$ ,  $@T_A = +25^\circ C$ , unless otherwise specified.)



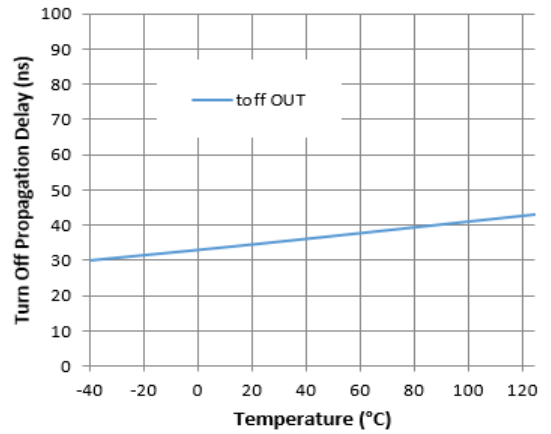
**Figure 2.** Turn-on Propagation Delay vs. Supply Voltage



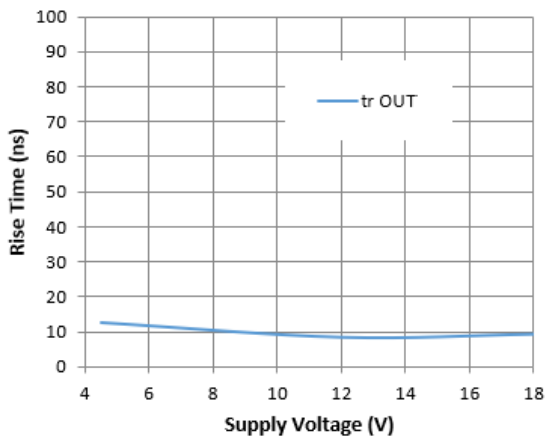
**Figure 3.** Turn-on Propagation Delay vs. Temperature



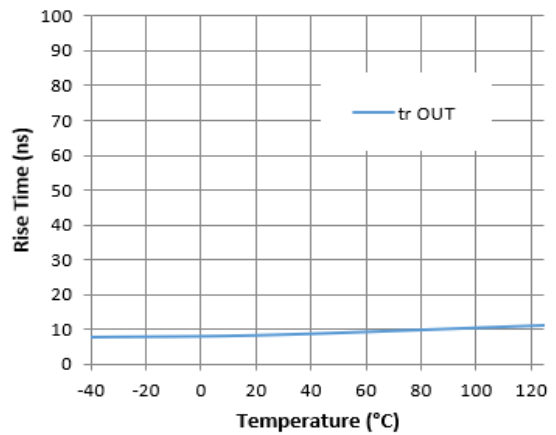
**Figure 4.** Turn-off Propagation Delay vs. Supply Voltage



**Figure 5.** Turn-off Propagation Delay vs. Temperature

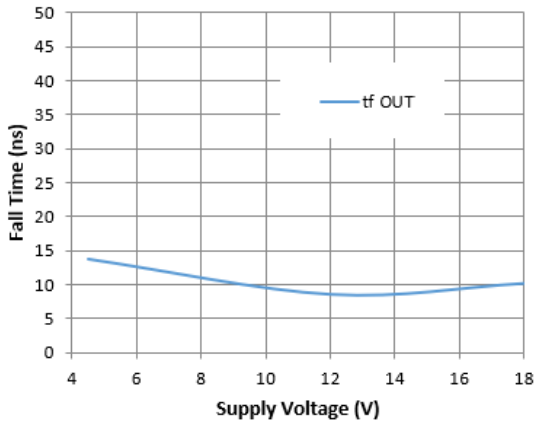


**Figure 6.** Rise Time vs. Supply Voltage

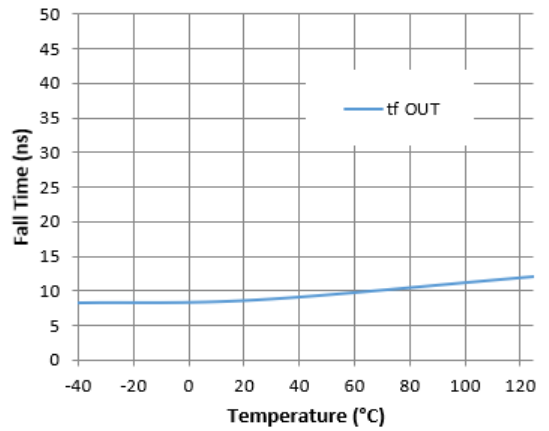


**Figure 7.** Rise Time vs. Temperature

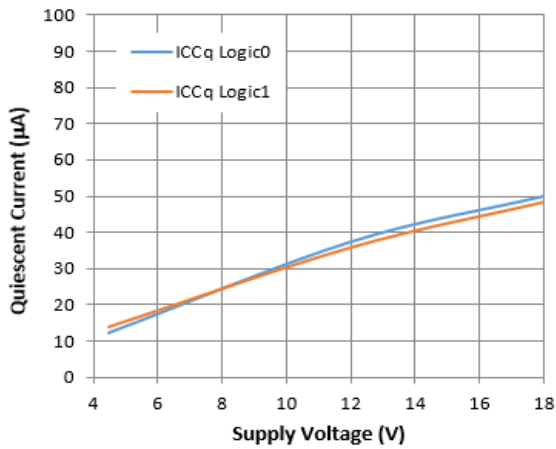
**Typical Performance Characteristics** (continued)



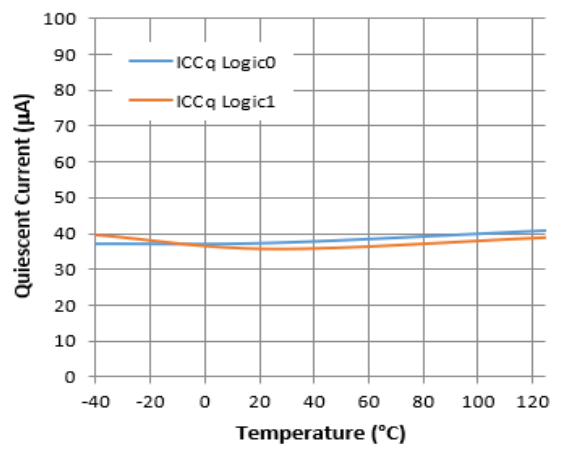
**Figure 8.** Fall Time vs. Supply Voltage



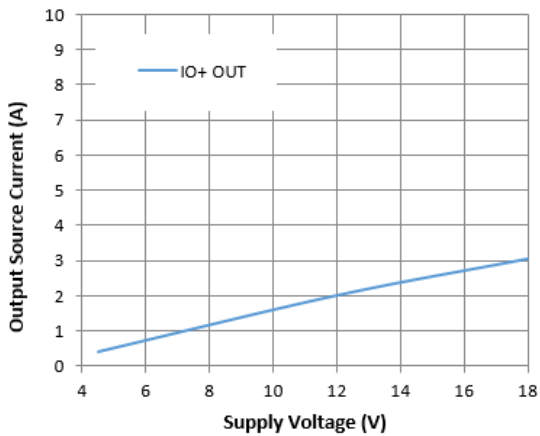
**Figure 9.** Fall Time vs. Temperature



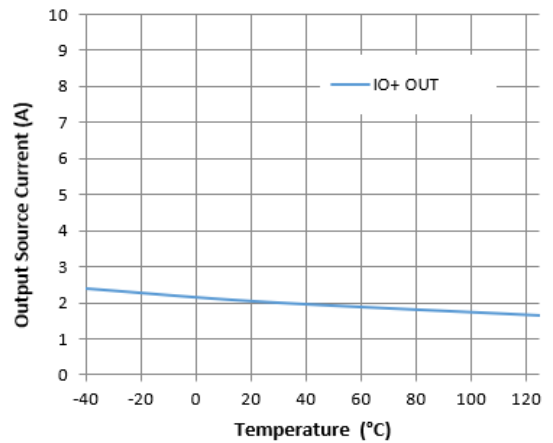
**Figure 10.** Quiescent Current vs. Supply Voltage



**Figure 11.** Quiescent Current vs. Temperature

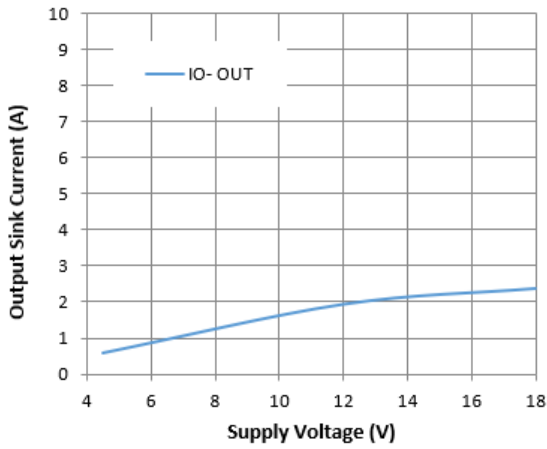


**Figure 12.** Output Source Current vs. Supply Voltage

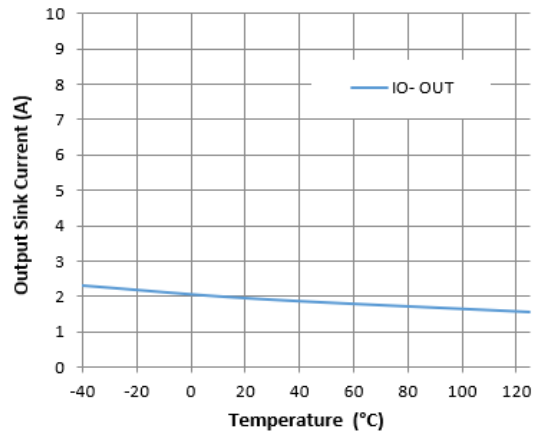


**Figure 13.** Output Source Current vs. Temperature

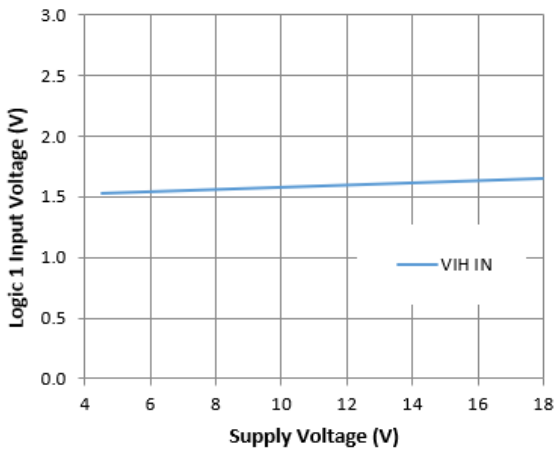
**Typical Performance Characteristics** (continued)



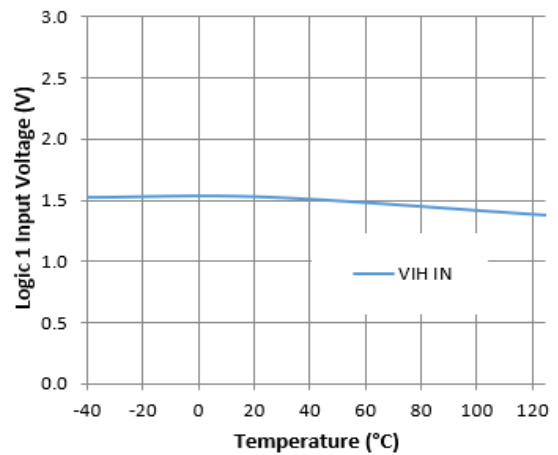
**Figure 14.** Output Sink Current vs. Supply Voltage



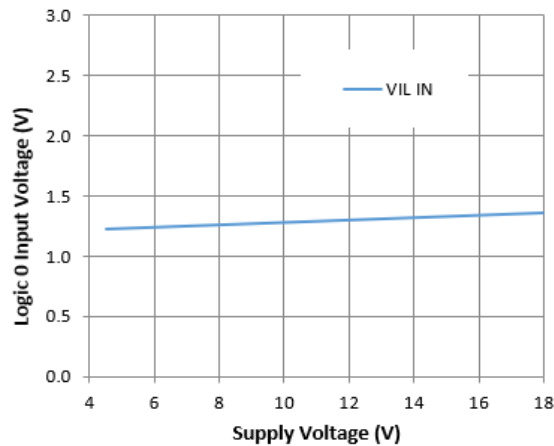
**Figure 15.** Output Sink Current vs. Temperature



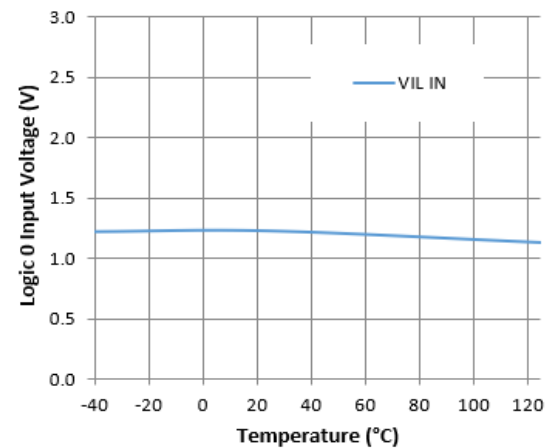
**Figure 16.** Logic 1 Input Voltage vs. Supply Voltage



**Figure 17.** Logic 1 Input Voltage vs. Temperature



**Figure 18.** Logic 0 Input Voltage vs. Supply Voltage



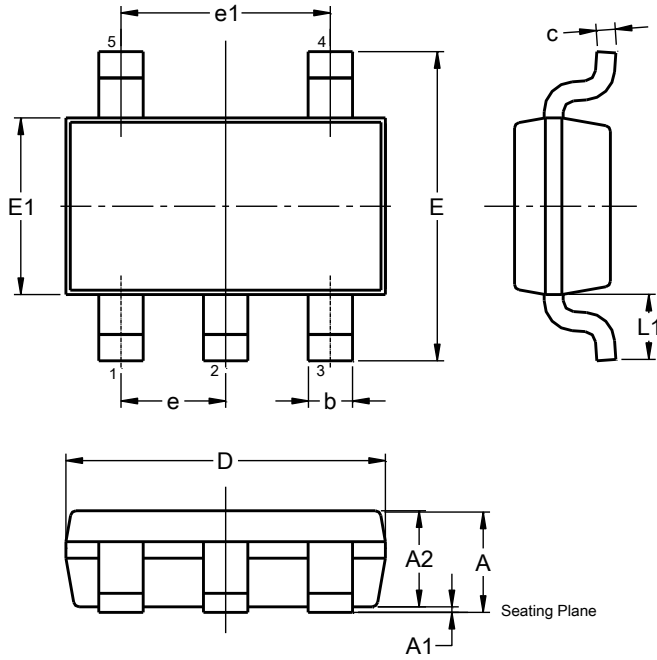
**Figure 19.** Logic 0 Input Voltage vs. Temperature



**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**TSOT25 (Type TH)**

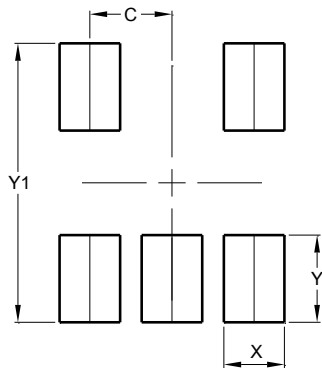


TSOT25 (Type TH)			
Dim	Min	Max	Typ
A	--	1.10	--
A1	0.01	0.10	--
A2	0.70	1.00	0.90
b	0.30	0.50	--
c	0.08	0.20	--
D	2.90 BSC		
E	2.80 BSC		
E1	1.60 BSC		
e	0.95 BSC		
e1	1.90 BSC		
L1	0.60 REF		
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**TSOT25 (Type TH)**



Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199

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